

REMARKS/ARGUMENTS

Favorable consideration of this application, as presently amended and in light of the following discussion, is respectfully requested.

Claims 9, 32, 34, 36, 39 and 40 are presently pending in this application, Claims 9 and 36 having been amended by the present amendment.

In the outstanding Office Action, Claims 9 and 36 were rejected under 35 U.S.C. §102(e) as being anticipated by Iwasaki et al. (U.S. Patent 6,447,038). However, Claims 32, 34, 39 and 40 were indicated as allowed.

First, Applicants acknowledge with appreciation the indication that Claims 32, 34, 39 and 40 have been allowed. However, regarding Claims 9 and 36, Applicants believe that Claims 9 and 36 as currently amended include allowable subject matter as discussed below.

Claims 9 and 36 have been amended herein. It is believed that these amendments find support in the specification, claims and drawings as originally filed, and no new matter is believed to be added thereby. If, however, the Examiner disagrees, the Examiner is invited to telephone the undersigned who will be happy to work in a joint effort to derive mutually satisfactory claim language.

Before addressing the outstanding rejection, a brief recapitulation of Claim 9 as currently amended is believed to be helpful. Amended Claim 9 is directed to a multilayered printed circuit board and recites: "a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer, wherein said solder resist layer contains an elastomer component and at least one resin selected from the group consisting of a thermoplastic resin and a thermosetting resin, and said elastomer component is separated in micro-phase as to form an island-in-sea structure after curing in said solder resist layer." By providing such a

solder resist layer, the solder resist layer significantly ameliorates stress and is made less fragile.

Iwasaki et al. is directed to an electronic appliance. Nevertheless, Iwasaki et al. does not teach or suggest “a solder resist layer formed as an outermost layer, wherein said solder resist layer contains an elastomer component and at least one resin selected from the group consisting of a thermoplastic resin and a thermosetting resin, and said elastomer component is separated in micro-phase as to form an island-in-sea structure after curing in said solder resist layer” as recited in amended Claim 9. On the other hand, Iwasaki et al. merely describes a solder resist 8b containing a repellent such as pyrethroid and other neurotransmitters.¹ Therefore, the subject matter recited in Claim 9 is believed to be clearly distinguishable from Iwasaki et al. and thus is neither anticipated by nor rendered obvious over Iwasaki et al.

Likewise, Claim 36 recites, *inter alia*, “a solder resist layer formed as an outermost layer, wherein said solder resist layer contains an elastomer component and at least one resin selected from the group consisting of a thermoplastic resin and a thermosetting resin” and thus is also distinguishable from Iwasaki et al.

For the foregoing reasons, Claims 9 and 36 are believed to be allowable.

Finally, the attention of the Patent Office is directed to the following address of Applicants’ new representative:

Oblon, Spivak, McClelland, Maier & Neustadt, P.C.
1940 Duke Street
Alexandria, VA 22314.

Please direct all future communications to this address.

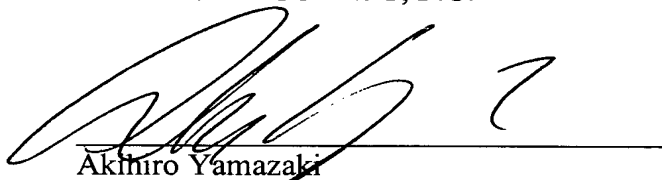
¹ Iwasaki et al., column 7, line 11, to column 9, line 31.

Application No. 10/049,270
Reply to Office Action of April 6, 2007

In light of the prior indication of allowable claims and in view of the amendments presented above, the present application is believed to be in condition for allowance, and an early action favorable to that effect is earnestly solicited.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.

A handwritten signature in black ink, appearing to read 'Akihiro Yamazaki', is written over a horizontal line.

Akihiro Yamazaki
Attorneys of Record
Registration No. 46,155

Customer Number
22850

Tel: (703) 413-3000
Fax: (703) 413 -2220
(OSMMN 06/04)

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